

# HEXFRED ULTRAFAST, SOFT RECOVERY DIODE

#### Features

- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters
- Hermetically Sealed
- Ceramic Eyelets

## Description

These Ultrafast, soft recovery diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

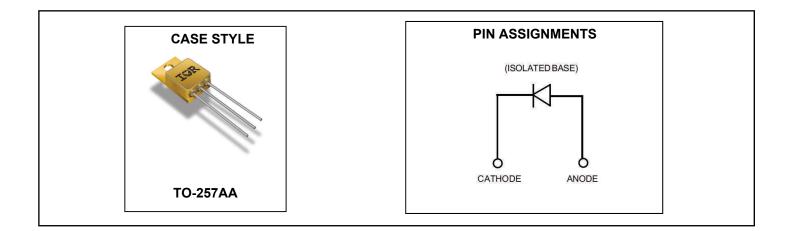
## Absolute Maximum Ratings

Characteristics	acteristics Parameter		Units
V <sub>R</sub>	Cathode to Anode Voltage	200	V
I <sub>F (AV)</sub>	Continuous Forward Current, T <sub>C</sub> = 120°C ①	16	А
I <sub>FSM</sub>	Single Pulse Forward Current , $T_c = 25^{\circ}C$ ②	140	А
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Maximum Power Dissipation	100	W
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature Range	-55 to 150	°C

#### Notes:

① D.C. = 50% rectangle wave

@ 1/2 sine wave, 60Hz, Pulse Width = 8.33ms



PD-94222B

# HFB16HY20C

 $V_R$  = 200V  $I_{F(AV)}$  = 16A  $t_{rr}$  = 35ns



Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
V <sub>BR</sub>	Cathode Anode Breakdown Voltage	200			V	I <sub>R</sub> = 100μA
V <sub>FM</sub>	Max Forward Voltage See Fig. 1			1.29		I <sub>F</sub> = 16A, T <sub>J</sub> = -55°C
				1.17		I <sub>F</sub> = 16A, T <sub>J</sub> = 25°C
				1.52	V	I <sub>F</sub> = 32A, T <sub>J</sub> = 25°C
				1.48		I <sub>F</sub> = 32A, T <sub>J</sub> = 125°C
I <sub>RM</sub>	Max Reverse Leakage Current			10	μA	$V_R = V_R$ Rated
	See Fig. 2			200	μA	$V_R = V_R$ Rated, $T_J = 125^{\circ}C$
CT	Junction Capacitance, See Fig. 3			200	pF	$V_{R} = 200V$
Ls	Series Inductance		9.8		nH	Measured from anode lead to Cathode lead, 6mm (0.25 in) from package

# Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

# Dynamic Recovery Characteristics @ $T_J = 25^{\circ}C$ (unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions		
t <sub>rr</sub>	Reverse Recovery Time			35	ns	$I_F = 0.5A, V_R = 30V, di_f/dt = 250A/\mu s$		
t <sub>rr1</sub>	Reverse Recovery Time		42		20	T <sub>J</sub> = 25°C	1 - 164	
t <sub>rr2</sub>	See Fig. 5		61		ns	T <sub>J</sub> = 125°C	I <sub>F</sub> = 16A	
I <sub>RRM1</sub>	Peak Recovery Current		4.6		А	T <sub>J</sub> = 25°C	V <sub>R</sub> = 160V	
I <sub>RRM2</sub>	See Fig. 6		8.4		A	T <sub>J</sub> = 125°C	VR - 100V	
Q <sub>rr1</sub>	Reverse Recovery Charge		105		nC	T <sub>J</sub> = 25°C	− di <sub>f</sub> /dt = 200A/μs	
Q <sub>rr2</sub>	See Fig. 7		280		ne	T <sub>J</sub> = 125°C		
di <sub>(rec)M</sub> /dt1	Peak Rate of Fall of Recovery Current		360		A /	T <sub>J</sub> = 25°C		
di <sub>(rec)M</sub> /dt1	During tb - See Fig. 8		685		A/µs	T <sub>J</sub> = 125°C		

## **Thermal - Mechanical Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case, See Fig. 4		1.25	°C/W
Wt	Weight	4.3		g



200

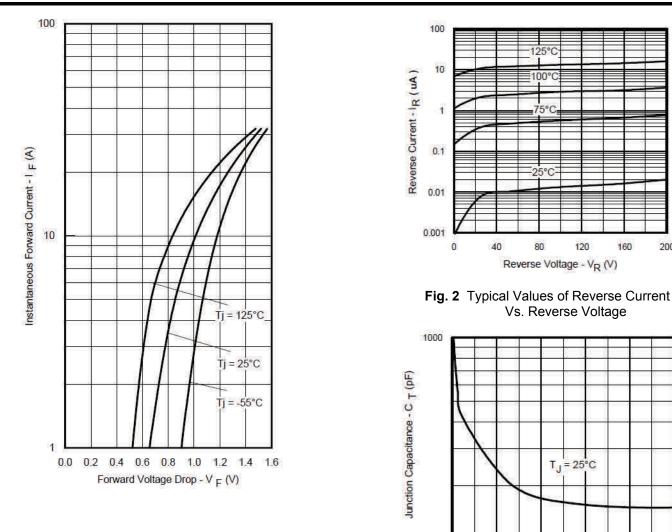


Fig. 1 Max. Forward Voltage Drop Characteristics

Fig. 3 Typical Junction Capacitance Vs. Reverse Voltage

80

Reverse Voltage - VR (V)

120

160

200

100

0

40

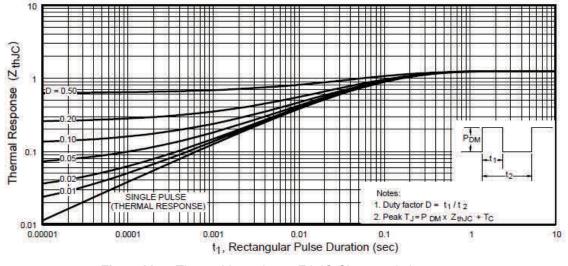


Fig. 4 Max. Thermal Impedance ZthJC Characteristics



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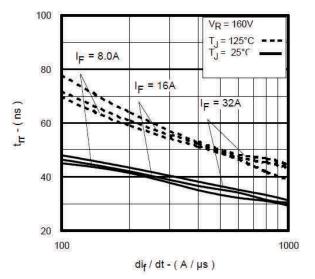
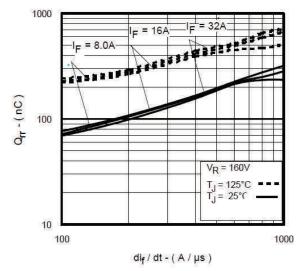
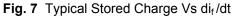


Fig. 5 Typical Reverse Recovery Vs di<sub>f</sub>/dt





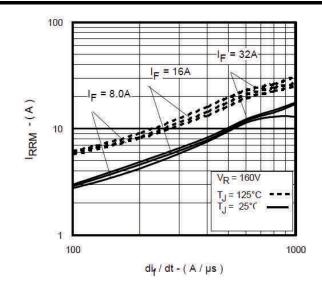


Fig. 6 Typical Recovery Current Vs di<sub>f</sub>/dt

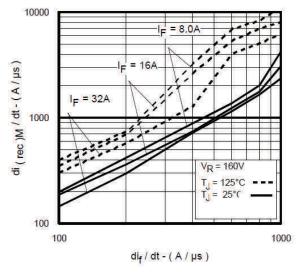
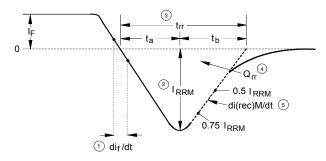


Fig. 8 Typical  $di_{(rec)M}/dt Vs di_f/dt$ 



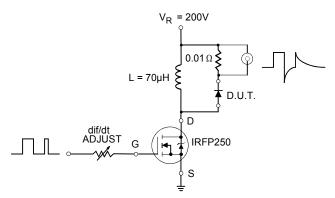


Fig. 9 Typical Reverse Recovery Parameter Test Circuit

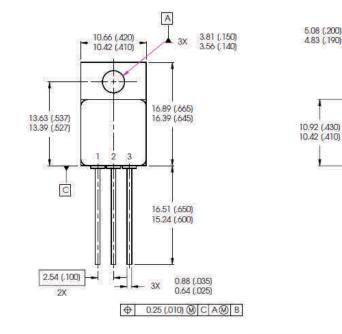
- ① di<sub>f</sub> /dt Rate of change of current through zero crossing.
- ② I<sub>RRM</sub> Peak reverse recovery current.
- 3 t<sub>rr</sub> Reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75I<sub>RRM</sub> and 0.5I<sub>RRM</sub> extrapolated to zero current.
- $\circledast~Q_{rr}$  Area under curve defined by  $t_{rr}$  and  $I_{RRM}\,$   $Q_{rr}\,$  =  $(t_{rr}\,$  \_X  $I_{RRM})$  / 2
- $\ensuremath{\textcircled{}^\circ}$  di\_{(rec)M}/dt Peak rate of change of current during  $t_b$  position of  $t_{rr}.$

Fig. 10 Reverse Recovery Waveform and Definitions

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#### Case Outline and Dimensions — TO-257AA



#### NOTES:

1. DIMENSIONING & TOLER ANCING PER ANSI Y14.5M-1994.

2. CONTROLLING DIMENSION: INCH.

3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

4. OUTLINE CONFORMS TO JEDEC OUTLINE TO-257AA.

LEAD ASSIGNMENTS 1=CATHODE

2 = NO CONNECTION 3 = ANODE ∠7 0.13 (.005)

1.14 (.045)

0.89 (.035)

В

0.889 (.035)

MAX.

3.05 (.120)



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